Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	0	((fluorocarbon near dielectric) near8 contaminant) and ("carbon dioxide" near4 (fluid or liquid)) and (solvent or alcohol)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 11:07
S2	2	(fluorocarbon near dielectric) and ("carbon dioxide" near4 (fluid or liquid)) and (solvent or alcohol)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 11:26
S3	2	(substrate or semiconductor or wafer) and (fluorocarbon near dielectric) and ("carbon dioxide" near4 (fluid or liquid)) and (solvent or alcohol)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 11:42
S4	409	(substrate or semiconductor or wafer) and fluorocarbon and ("carbon dioxide" near4 (fluid or liquid)) and (solvent or alcohol)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 11:42
S5	297	(substrate or semiconductor or wafer) and fluorocarbon and ("carbon dioxide" near4 (fluid or liquid)) and (solvent or alcohol) and supercritical	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 11:43
S6	30	(substrate or semiconductor or wafer) and fluorocarbon and ("carbon dioxide" near4 (fluid or liquid)) and (solvent or alcohol) and supercritical and water and hydrofluorocarbon	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 11:43
S7	21	(substrate or semiconductor or wafer) and fluorocarbon and ("carbon dioxide" near4 (fluid or liquid)) and (solvent or alcohol) and supercritical and water and hydrofluorocarbon and (butanol or methanol or ethanol or propanol)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 12:10

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S8		(substrate or semiconductor or wafer) and fluorocarbon and ("carbon dioxide" near4 (fluid or liquid)) and silane and "nitrated fluorocarbon"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 12:10
S9	0	(substrate or semiconductor or wafer) and fluorocarbon and ("carbon dioxide" near4 (fluid or liquid)) and silane and "NFC"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 12:11
S10	0	(substrate or semiconductor or wafer) and fluorocarbon and ("carbon dioxide" near4 (fluid or liquid)) and silane and (nitrat\$4 near4 hydrocarbon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 12:11
S11	36	silane and (nitrat\$4 near4 hydrocarbon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 12:11
S12	13	silane and (nitrat\$4 near4 hydrocarbon) and (via or trench)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 12:11
S13	15	silane and (nitrat\$4 near4 hydrocarbon) and (via or trench or hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 12:12
S14	0	silane and (nitrat\$4 near4 hydrocarbon) and (via or trench or hole) and ("carbon dioxide" near4 fluid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 12:12
S15	0	silane and (nitrat\$4 near4 hydrocarbon) and (via or trench or hole) and ("carbon dioxide" near8 fluid)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 12:12

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S16	15	silane and (nitrat\$4 near4 hydrocarbon) and (via or trench or hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/03 12:13
S17	161	(semiconductor or substrate or wafer) near8 (fluorocarbon near4 (dielectric or oxide or insulat\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 09:41
S18	30	(semiconductor or substrate or wafer) near8 (fluorocarbon near4 (dielectric or oxide or insulat\$4)) and (CH or Hsub2O or OH or HF)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 09:44
S19	0	(semiconductor or substrate or wafer) near8 (fluorocarbon near4 (dielectric or oxide or insulat\$4)) and (CH or Hsub2O or OH or HF) and (treat near8 "carbon dioxide")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 09:45
S20	0	(semiconductor or substrate or wafer) near8 (fluorocarbon near4 (dielectric or oxide or insulat\$4)) and (CH or Hsub2O or OH or HF) and (treat near12 "carbon dioxide")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 09:45
S21	9	(semiconductor or substrate or wafer) near8 (fluorocarbon near4 (dielectric or oxide or insulat\$4)) and (CH or Hsub2O or OH or HF) and "carbon dioxide"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 09:45
S22	0	(semiconductor or substrate or wafer) near8 (fluorocarbon near4 (dielectric or oxide or insulat\$4)) and (CH or Hsub2O or OH or HF) and "carbon dioxide" and alcohol	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 09:46

S23	1	(semiconductor or substrate or wafer) near8 (fluorocarbon near4 (dielectric or oxide or insulat\$4)) and (CH or Hsub2O or OH or HF) and "carbon dioxide" and (alcohol or methanol or ethanol or propanol or butanol)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 09:50
S24	1	(semiconductor or substrate or wafer) near8 ((fluorocarbon or CF) near4 (dielectric or oxide or insulat\$4)) and (CH or Hsub2O or OH or HF) and "carbon dioxide" and (alcohol or methanol or ethanol or propanol or butanol)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 09:51
S25	60	(semiconductor or substrate or wafer) near8 (fluorocarbon or CF) and (CH or Hsub2O or OH or HF) and "carbon dioxide" and (alcohol or methanol or ethanol or propanol or butanol)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 09:54
S26	68	(semiconductor or substrate or wafer) near8 (fluorocarbon or CF) and (CH or Hsub2O or OH or HF) and "carbon dioxide" and (alcohol or methanol or ethanol or propanol or butanol or silane)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 09:59
S27	15	(semiconductor or substrate or wafer) near8 (fluorocarbon or CF) and (CH or Hsub2O or OH or HF) and "carbon dioxide" and ((alcohol or methanol or ethanol or propanol or butanol or silane) near4 liquid)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 10:00
S28	40	(semiconductor or substrate or wafer) near8 (fluorocarbon or CF) and (CH or Hsub2O or OH or HF) and "carbon dioxide" and ((alcohol or methanol or ethanol or propanol or butanol or silane) near4 (liquid or solvent))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 10:06
S29	10	(semiconductor or substrate or wafer) near8 (fluorocarbon or CF) and (CH or Hsub2O or OH or HF) and ("carbon dioxide" near4 liquid)and ((alcohol or methanol or ethanol or propanol or butanol or silane) near4 (liquid or solvent))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 11:02

S30	10	(fluorocarbon or CF) near8 (semiconductor or substrate or wafer) and (CH or Hsub2O or OH or HF) and ("carbon dioxide" near4 liquid) and ((alcohol or methanol or ethanol or propanol or butanol or silane) near4 (liquid or solvent))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 11:04
S31	25	(fluorocarbon or CF) near8 (semiconductor or substrate or wafer) and ("carbon dioxide" near4 liquid) and ((alcohol or methanol or ethanol or propanol or butanol or silane) near4 (liquid or solvent))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 11:06
S32	23	(fluorocarbon or CF) near8 (semiconductor or substrate or wafer) and ("carbon dioxide" near4 liquid) and ((alcohol or methanol or ethanol or propanol or butanol or silane) near4 (liquid or solvent)) and (via or trench or hole)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 11:55
S33	4	(fluorocarbon or CF) near8 (semiconductor or substrate or wafer) and ("carbon dioxide" near4 liquid) and ((alcohol or methanol or ethanol or propanol or butanol or silane) near4 (liquid or solvent)) and (opening or trench or hole)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/20 11:56